



xESD - Nano-engineered ESD resin for Isotropic Static Dissipative Performance

xESD is a black, rigid, static-dissipative photopolymer resin using a urethane dimethacrylate base that includes a stable dispersion of discrete functionalized carbon nanotubes to achieve consistent static dissipative properties. This dispersion does not settle in xESD resin, resulting in consistent ESD-capable parts. The discrete nature of xESD also produces parts that leave no carbon trails and improves key mechanical properties such as tensile strength, modulus, and impact resistance. xESD is designed for use with LSPc®Technology and allows for high resolution part fabrication with isotropic static dissipative and mechanical properties.



Part Properties

	Metric	Imperial	Method
Mechanical Properties			
Tensile Strength	68.1 MPa	9880 psi	ASTM D 638-14
Tensile Modulus	2.6 GPa	380 ksi	ASTM D 638-14
Yield Strength	40.6 MPa	5880 psi	ASTM D 638-14
Elongation at Break	3.8 %	3.8 %	ASTM D 638-14
Flexural Properties			
Flexural Strength	97.4 MPa	14,100 psi	ASTM D 790-15*
Flexural Modulus	1.8 GPa	260 ksi	ASTM D 790-15*
Impact Properties			
Notched IZOD	24 J/m	0.45 ft-lbf/in	ASTM D 256-10
Hardness			
Shore "D"	87	87	ASTM D 2240-15
Thermal Properties			
Heat Deflection @1.8MPa	91.4 °C	196.5 °F	ASTM D 648-16
Heat Deflection @0.45MPa	91.3 °C	196.3 °F	ASTM D 648-16
Electrical Properties			
Surface Resistance	10 ⁷ Ω	10 ⁷ Ω	ASTM D 257

*Specimens did not yield or break within the 5% strain limit when tested by Procedure A, the increased strain was applied (Procedure B) to induce yield and/or break within the required 5% strain limit



Resin Properties

Other Properties	Value		Condition
	Metric	Imperial	
Water Absorption	0.9%	0.9%	ASTM D 570-98
Density	1.1 g/cm ³	0.04 lbs/in ³	25°C
Viscosity	878.1 cps	878.1 cps	25°C

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